

DATA SHEET

CURRENT SENSOR-LOW TCR

PL0805 1mR

5%,1%

size 080<u>5</u>

RoHS Compliant & Halogen Free



YAGEO Phicomp

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Chip Resistor Surface Mount

PL SERIES

0805

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SCOPE

This specification describes PL0805 current sensor – low TCR chip resistors with lead-free terminations.

APPLICATIONS

- Power supplies
- Consumer(Mobile \ PNDs \ ...)
- Laptop
- HDDs

FEATURES

- Products with lead free terminations meet RoHS requirements.
- High component and equipment reliability with high power rating.
- Low resistance and narrow tolerance can suitable for current detection.

ORDERING INFORMATION - GLOBAL PART NUMBER

Part number is identified by the series name, size, tolerance, packaging type, temperature coefficient of resistance, taping reel, resistance value.

PL0805 $\frac{X}{(1)}$ $\frac{X}{(2)}$ $\frac{X}{(3)}$ $\frac{XX}{(4)}$ $\frac{XXXX}{(5)}$ $\frac{L}{(6)}$

(1) TOLERANCE

 $F = \pm 1\%$

 $J = \pm 5\%$

(2) PACKAGING TYPE

R = Paper taping reel

(3)TEMPERATURE COEFFICIENT OF RESISTANCE

I=±300ppm/°C

(4) TAPING REEL

47 = 7 inch dia. Reel & Power Rating 0.5W

(5) RESISTANCE VALUE

0R001 (1mR)

(6) DEFAULT CODE

Letter L is system default code for order only (NOTE)

ORDERING EXAMPLE

The ordering code for a PL0805 0.5W chip resistor, TC300 value 0.001 Ω (1mR) with ±1% tolerance, supplied in 7-inch tape reel with 5Kpcs quantify is: PL0805FRI470R001L.

NOTE

- 1. All our RSMD products meet RoHS compliant and Halogen Free. "LFP" of the internal 2D reel label mentions "Lead Free Process".
- 2. On customized label, "LFP" or specific symbol can be printed.

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MARKING

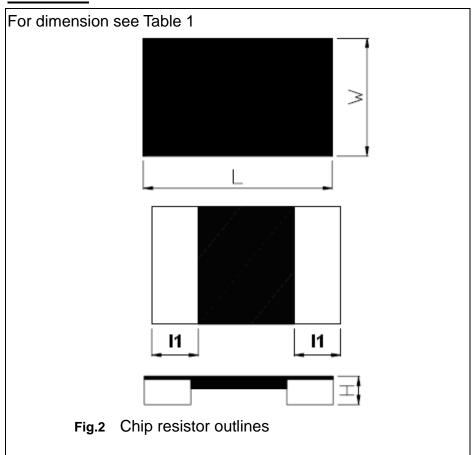
PL0805



_Fig.1

No marking

OUTLINES



DIMENSIONS

_ Table 1

l	1mR
L (mm)	2.03±0.20
W (mm)	1.27±0.20
H (mm)	≤0.4
l1 (mm)	0.6 ±0.15

ELECTRICAL CHARACTERISTICS

Table 2	
CHARACTERISTICS	PL0805
Operating Temperature Range	–55°C to +155°C
Maximum Working Voltage	$\sqrt{(P^*R)}$
Resistance Range	1mΩ
Temperature Coefficient	±300ppm/°C

PACKING STYLE AND PACKAGING QUANTITY

Table 3				
PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL	
PL0805	Paper taping reel	7" (178 mm)	5,000 Units	

FUNCTIONAL DESCRIPTION

POWER RATING

PL0805 rated power at 70°C is 0.5W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$U=\sqrt{(P^*R)}$$

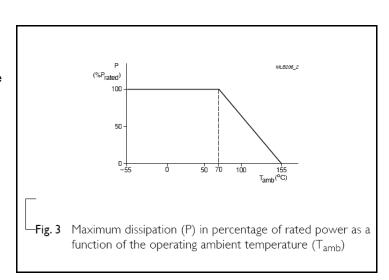
Where

U=Continuous rated DC

or AC (rms) working voltage (v)

P=Rated power

R=Resistance value (Ω)



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TAPING REEL

_ Table 4

DIMENSION	PL0805
Tape Width(mm)	8
ØA (mm)	178.0±1.0
ØN (mm)	60.0+1/-0
ØC (mm)	13.5±0.5
ØD (mm)	21.0±0.8
W1 (mm)	9.0±0.5

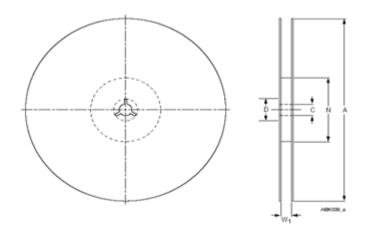


Fig.4 Reel

PAPER/PE TAPE SPECIFICATION

_ Table 5

PL0805	
1.60±0.15	
2.30±0.15	
8.00±0.30	
1.75±0.10	cover
3.50±0.10	
4.00±0.10	
4.00±0.10	
2.00±0.10	
1.50±0.10	
0.50±0.10	
	1.60±0.15 2.30±0.15 8.00±0.30 1.75±0.10 3.50±0.10 4.00±0.10 2.00±0.10 1.50±0.10

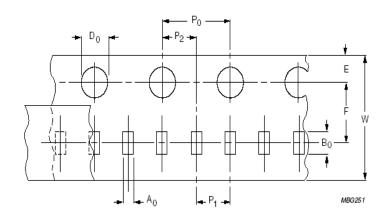


Fig.5 Paper/PE tape

FOOTPRINT DIMENSION

Size Footprint	Dimensions		Code	unit :mm
PL0805	а	b		i
1mΩ	2.10	1.50		0.80

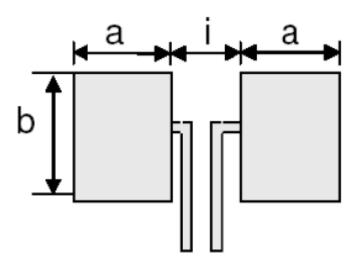


Fig.6 Recommended Footprint Dimensions

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TESTS AND REQUIREMENTS

TEST	TEST METHOD	PROCEDURE	REQUIREMENT
Life/ Endurance	IEC 60115-1 4.25.1	1,000 hours at 70±5 °C applied rated power 1.5 hours on, 0.5 hour off.	± (1.0 % + 0.0005Ω)
High Temperature Exposure/Endurance at upper category temperature	IEC 60068-2-2	1,000 hours at 155±5 °C,unpowered.	± (1.0 % + 0.0005Ω)
Moisture Resistance	MIL-STD-202 Method 106G	Each temperature / humidity cycle is defined at 8 hours (Method 106G), 3 cycles / 24 hours for 10d. with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, un-powered Parts mounted on test-boards, without condensation on parts Measurement at 24±2 hours after test conclusion.	± (0.5% + 0.0005Ω)
Thermal Shock	MIL-STD-202 Method 107G	-55/+125 °C Note: Number of cycles required is 300. Devices mounted Maximum transfer time is 20 seconds. Dwell time is 15 minutes. Air – Air	± (1.0% + 0.0005Ω)
Short time overload	IEC 60115-1 4.13	Applied 5 times of rating power 5 seconds at room temperature	\pm (0.5% + 0.0005 Ω) No visible damage
Board Flex/ Bending	IEC 60068-2-21	Chips mounted on a glass epoxy resin PCB(FR4) 2 mm bending Bending time: 60±1 seconds	± (1.0 % + 0.0005Ω)
Solderability - Wetting	J-STD-002 test B	Electrical Test not required Magnification 50X SMD conditions: 1st step: Method B, aging 4 hours at 155 °C dry heat 2nd step: leadfree solder bath at 245±3 °C Dipping time: 3±0.5 seconds	Well tinned (≥95% covered) No visible damage
-Leaching	J-STD-002 test D	Leadfree solder, 260 °C, 30 seconds immersion time	No visible damage
-Resistance to Soldering Heat	IEC 60068-2-58	Specimen passed 3 times reflow temperature at 260°C, with solder.	\pm (0.5% + 0.0005 Ω) No visible damage

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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	2023-07-20		- First issue of this specification



单击下面可查看定价,库存,交付和生命周期等信息

>>Yageo(国巨)